L	Hits	Search Text	DB	Time stamp
Number				-
1	3	438/15,687,683,762,763.ccls. and	USPAT;	2004/03/15 15:10
		<pre>(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy)</pre>	US-PGPUB; EPO; JPO;	15:10
	•	or ubm) and (solder) and (wire) and	DERWENT	
		(barrier)		
2	10	257/737,738,613,761.ccls. and (integrated	USPAT;	2004/03/15
l		adj circuit) and (contact adj pad) and	US-PGPUB;	15:12
		((under adj bump adj metallurgy) or ubm)	EPO; JPO;	
	6039	and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj	DERWENT USPAT;	2003/01/30
-	6039	pad) and (under adj bump adj region or	US-PGPUB;	15:08
		layer)	EPO; JPO;	
		•	DERWENT	
-	0		USPAT;	2003/01/30
		pad) and (under adj bump adj region or	US-PGPUB;	15:10
		layer) and (solder adj bonds) and (wire adj bomds)	EPO; JPO; DERWENT	
_ i	184	adj bomds; (integrated adj circuit) and (contact or	USPAT;	2003/01/30
	101	output/input adj pads) and (under adj	US-PGPUB;	15:15
		bump adj region or layer) and (solder adj	EPO; JPO;	
	ا مدد	bonds) and (wire adj bonds)	DERWENT	2002/01/21
-	118		USPAT; US-PGPUB;	2003/01/31 10:15
		pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire	EPO; JPO;	10.10
	·	adj bonds)	DERWENT	
-	118	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31
1		pad) and (under adj bump adj region or	US-PGPUB;	10:25
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or layer) and (passivation adj region or	DERWENT	
		layer) and (passivation adj region of layer)		
-	0	"09888674" and (barrier)	USPAT;	2003/06/19
			US-PGPUB;	15:37
		, ·	EPO; JPO;	
	0	"00888674" and (harrier)	DERWENT USPAT;	2003/06/20
-	"	"09888674" and (barrier)	US-PGPUB;	10:14
	•		EPO; JPO;	
			DERWENT	
-	0	"09/888674" and (barrier)	USPAT;	2003/01/31
			US-PGPUB; EPO; JPO;	11:45
			DERWENT	
-	118		USPAT;	2003/07/07
		pad) and (under adj bump adj region or	US-PGPUB;	09:59
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or layer)		
_	0	l • '	USPAT;	2003/01/31
	ľ	pad) and ((under adj bump adj metallurgy)	US-PGPUB;	12:24
		or ubm) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier) and	DERWENT	
!	0	(passivation) (integrated adj circuit) and (contact adj	USPAT;	2003/01/31
-		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	12:25
		or ubm) and (solder adj bonds) and (wire	EPO; JPO;	,
		adj bonds) and (barrier)	DERWENT	
-	4	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	12:26
		or ubm) and (solder) and (wire adj bonds) and (barrier)	EPO; JPO; DERWENT	
_	28	and (balliel) (integrated adj circuit) and (contact adj	USPAT;	2003/02/01
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	15:10
		or ubm) and (solder) and (wire) and	EPO; JPO;	
		(barrier)	DERWENT	<u> </u>

_	118	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31
		pad) and (under adj bump adj region or	US-PGPUB;	15:38
		layer) and (solder adj bonds) and (wire	EPO; JPO;	1
		adj bonds) and (barrier adj region or	DERWENT	
1		layer) and (passivation adj region or		
		layer)		
_	23	(integrated adj circuit) and (contact adj	USPAT;	2003/07/07
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	10:03
		or ubm) and (solder) and (wire) and	EPO; JPO;	
		(barrier) and (lead)	DERWENT	
l _	. 0	438/15.ccls. and (integrated adj circuit)	USPAT;	2003/05/30
	' "	and (contact adj pad) and ((under adj	US-PGPUB;	18:38
		bump adj metallurgy) or ubm) and (solder)	EPO; JPO;	
	İ	and (wire) and (barrier)	DERWENT	
_	0	438/15,762,763.ccls. and (integrated adj	USPAT;	2004/03/15
-		circuit) and (contact adj pad) and	US-PGPUB;	15:09
		((under adj bump adj metallurgy) or ubm)	EPO; JPO;	10.05
		and (solder) and (wire) and (barrier)	DERWENT	
[and (Solder) and (wire) and (ballier)	USPAT;	2004/03/15
-	4	257/737.ccls. and (integrated adj	US-PGPUB;	15:11
		circuit) and (contact adj pad) and		15:11
		((under adj bump adj metallurgy) or ubm)	EPO; JPO;	
1		and (solder) and (wire) and (barrier)	DERWENT	2002/05/20
-	27	(integrated adj circuit) and (contact adj	USPAT;	2003/05/30
	1	pad) and ((under adj bump adj metallurgy)	US-PGPUB;	18:01
		or ubm) and (solder) and (wire) and	EPO; JPO;	
1		(barrier) and (lead)	DERWENT	0000 (05 (00
-	0	438/15.ccls. and (integrated adj circuit)	USPAT;	2003/05/30
		and (contact adj pad) and ((under adj	US-PGPUB;	18:44
		bump adj metallurgy) or ubm) and (solder)	EPO; JPO;	
		and (wire) and (barrier)	DERWENT	1
-	123	(integrated adj circuit) and (contact adj	USPAT;	2003/05/30
		pad) and (under adj bump adj region or	US-PGPUB;	18:41
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or		1
		layer)		1
_	4	257/737.ccls. and (integrated adj	USPAT;	2003/05/30
	İ	circuit) and (contact adj pad) and	US-PGPUB;	18:51
		((under adj bump adj metallurgy) or ubm)	EPO; JPO;	
		and (solder) and (wire) and (barrier)	DERWENT	
-	1 0		TTO D T M	2002/05/20
		430/13.CCIS. and (integrated adj circuit)	USPAT;	2003/05/30
			USPAT; US-PGPUB;	18:45
		and (contact adj pad) and ((under adj		
		and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder)	US-PGPUB;	
_	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	US-PGPUB; EPO; JPO;	
-		and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj	US-PGPUB; EPO; JPO; DERWENT	18:45
-		and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and	US-PGPUB; EPO; JPO; DERWENT USPAT;	18:45
_		and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO;	18:45
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB;	18:45
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT;	18:45 2003/05/30 19:03 2003/05/30
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO;	18:45 2003/05/30 19:03 2003/05/30
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31
-	8 4 36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42
-	8	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31
-	8 4 36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj) and (barrier adj layer) and (nickel	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42
-	8 4 36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43
-	8 4 36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer)	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21 2003/12/02
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21 2003/12/02
-	36 4 0	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold "20010011764" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21 2003/12/02 18:25
-	36	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21 2003/12/02 18:25
-	36 4 0	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold "20010011764" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21 2003/12/02 18:25
	36 4 0	and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/738.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) 257/762.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) (integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel adj barrier) and (solder adg layer) "6221682" and gold "20010011764" and gold	US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB;	18:45 2003/05/30 19:03 2003/05/30 19:04 2003/05/31 11:42 2003/05/31 11:43 2003/06/19 13:21 2003/12/02 18:25

- 0 "6441487" and (gold) USPAT; 15:37 2003/06/19 15:37 2003/06/19 15:37 2003/06/19 15:37 2003/06/19 15:38 2003/06/19 15:38 2003/06/19 15:38 2003/06/19 2003/06/20 2003/06/
Peo; JPo; Derwent USPAT; US-PGPUB; EPO; JPo; DERWENT USPAT; US-PGPUB; EPO; JPo; DERWENT US-PGPUB; EPO; JPo; DERW
- 9 "5234149" and (gold) - 9 "5234149" and (gold) - 6 "5234149" and (under adj bump) - 6 "5234149" and (under adj bump) - 0 5234149.pn. and (under adj bump) - 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 1 "5234149" and (reflow\$3) - 1 "5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 2003/06/20
- 9 "5234149" and (gold) - 0 "5234149" and (under adj bump) - 0 5234149.pn. and (under adj bump) - 0 5234149.pn. and (under adj bump) - 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 1 "5234149" and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-
US-PGPUB; EPO; JPO; DERWENT USPAT; EPO; J
Company
- 6 "5234149" and (under adj bump) - 0 5234149.pn. and (under adj bump) - 0 5234149.pn. and (under adj bump) - 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 1 "5234149" and (reflow\$3) - 10 "5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3) DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO
- 6 "5234149" and (under adj bump) - 0 5234149.pn. and (under adj bump) - 0 5234149.pn. and (under adj bump) - 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 10 "5234149" and (reflow\$3) - 0 5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; U
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/19 17:48 17:4
DERWENT USPAT; 2003/06/19 17:48 1 "20010011764" and (under adj bump) USPAT; 2003/06/19 19:18 1 "20010011764" and (electroplating) USPAT; 2003/06/19 19:18 1 "20010011764" and (electroplating) USPAT; 2003/06/19 19:19 1 "5234149" and (reflow\$3) USPAT; 2003/06/20 10:15 1 0 "5234149.pn. and (reflow\$3) USPAT; 2003/06/20 10:16 1 20010011764.pn. and (reflow\$3) USPAT; 2003/06/20 10:16 1 20010011764.pn. and (lead) USPAT; 2003/06/20 10:31 2 2003/06/20 10:31 2 2003/06/20 10:31 2 2003/06/20 10:31
- 0 5234149.pn. and (under adj bump) - 1 "20010011764" and (under adj bump) - 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 1 "20010011764" and (electroplating) - 1 "5234149" and (reflow\$3) - 1 "5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3)
US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; D
- 1 "20010011764" and (under adj bump)
- 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 1 "20010011764" and (electroplating) - 1 "5234149" and (reflow\$3) - 0 5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3)
- 1 "20010011764" and (under adj bump) - 1 "20010011764" and (electroplating) - 1 "20010011764" and (electroplating) - 1 "5234149" and (reflow\$3) - 0 5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3)
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EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO;
- 1 "20010011764" and (electroplating) - 10 "5234149" and (reflow\$3) - 0 5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3)
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 10:15 - 0 5234149.pn. and (reflow\$3) US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 10:15 - 0 5234149.pn. and (reflow\$3) US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 10:16 - 1 20010011764.pn. and (reflow\$3) USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT US-PGPUB; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; DE
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 10:15 - 0 5234149.pn. and (reflow\$3) US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 10:15 - 0 5234149.pn. and (reflow\$3) US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 10:16 - 1 20010011764.pn. and (reflow\$3) USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT US-PGPUB; DERWENT US-PGPUB; EPO; JPO; DERWENT US-PGPUB; DE
DERWENT USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT
- 10 "5234149" and (reflow\$3) - 0 5234149.pn. and (reflow\$3) - 0 5234149.pn. and (reflow\$3) - 1 20010011764.pn. and (reflow\$3) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (lead) - 1 20010011764.pn. and (reflow\$3)
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; U
EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 USPAT; 2003/06/20
DERWENT USPAT;
- 0 5234149.pn. and (reflow\$3)
US-PGPUB; 10:16 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20
EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 USPAT; 2003/06/20 USPAT; 2003/06/20
DERWENT USPAT;
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 USPAT; 2003/06/20
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; DERWENT USPAT; 2003/06/20 USPAT; 2003/06/20
DERWENT USPAT; 2003/06/20 US-PGPUB; EPO; JPO; DERWENT USPAT; 1 20010011764.pn. and (reflow\$3) USPAT; 2003/06/20
- 1 20010011764.pn. and (lead) USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/20
US-PGPUB; 10:34 EPO; JPO; DERWENT USPAT; 2003/06/20
EPO; JPO; DERWENT USPAT; 2003/06/20
DERWENT USPAT; 2003/06/20
1 20010011764.pn. and (reflow\$3) USPAT; 2003/06/20
1 20010011,011,011
EPO; JPO;
DERWENT
- 0 20010011764.pn. and (selective adj USPAT; 2003/06/20
electroplating) US-PGPUB; 11:05
EPO; JPO;
DERWENT 126 (integrated adj circuit) and (contact adj USPAT; 2003/07/07
120 \linesgracea aay orreare, and \constant any
pad) and (under adj bump adj region or US-PGPUB; 10:01 layer) and (solder adj bonds) and (wire EPO; JPO;
adj bonds) and (barrier adj region or DERWENT
layer) and (passivation adj region or
layer)
- 0 438/14,15,762,763.ccls. and (integrated USPAT; 2003/10/29
adj circuit) and (contact adj pad) and US-PGPUB; 11:25
((under adj bump adj metallurgy) or ubm) EPO; JPO;
and (solder) and (wire) and (barrier) DERWENT
- 32 (integrated adj circuit) and (contact adj USPAT; 2003/07/07 pad) and ((under adj bump adj metallurgy) US-PGPUB; 10:03
Paul and //ander and many many and and and and and and and and and and
or ubm) and (solder) and (wire) and EPO; JPO; (barrier) and (lead) DERWENT
- 1103 ((bond adj pad) or terminal) near (copper USPAT; 2003/10/28
or Cu) US-PGPUB; 16:44
EPO; JPO;
DERWENT
- 545 ((bond adj pad) or terminal) near (copper USPAT; 2003/10/28
or Cu) and ((wire adj bonding) or wire) US-PGPUB; 16:46
EPO; JPO;
DERWENT

-	1	6133065.pn. and wire and solder	USPAT;	2003/12/02
		-	US-PGPUB;	18:10
			EPO; JPO;	
			DERWENT	
_	0	6133065.pn. and wire and solder and	USPAT;	2003/10/29
		underbump	US-PGPUB;	11:59
			EPO; JPO;	
	•		DERWENT	
_	0	6133065.pn. and underbump	USPAT;	2003/10/29
_	"	0155005.pm. and anderbamp	US-PGPUB;	12:09
			EPO; JPO;	
			DERWENT	
	1	6335104.pn. and wire and solder	USPAT;	2003/10/29
-	1	6535104.pm. and wire and sorder	US-PGPUB;	12:29
			EPO; JPO;	12.29
1				
		40.500.40	DERWENT	2003/10/29
-	2	4268849.pn.	USPAT;	1 · · · · · · · · · · · · · · · · · · ·
			US-PGPUB;	12:33
			EPO; JPO;	l
			DERWENT	
-	0	4268849.pn. and wire and solder	USPAT;	2003/10/29
			US-PGPUB;	12:34
			EPO; JPO;	
			DERWENT	
_	1	6335104.pn. and solder	USPAT;	2003/11/07
	1	•	US-PGPUB;	12:07
			EPO; JPO;	
			DERWENT	
_	1	20010011764.pn. and wire	USPAT;	2003/11/07
	1	20010011701.pii. ana 1120	US-PGPUB;	12:37
			EPO; JPO;	
ŀ			DERWENT	
	1	20010020745.pn. and wire	USPAT;	2003/11/07
-	1	20010020745.pn. and wife	US-PGPUB;	12:38
				12:30
			EPO; JPO;	
	_	, ,,	DERWENT	2002/11/07
-	1	20010020745.pn. and solder	USPAT;	2003/11/07
1			US-PGPUB;	12:38
			EPO; JPO;	i i
			DERWENT	0000/11/10
-	2	20020143830.pn.	USPAT;	2003/11/12
		_	US-PGPUB;	11:55
	1	<u> </u>	EPO; JPO;	
	1		DERWENT	1 2222 / 12 / 12
-	2	20030143830.pn.	USPAT;	2003/11/12
	1		US-PGPUB;	11:55
	1		EPO; JPO;	
1			DERWENT	
-	0	20030143830.pn. and solder	USPAT;	2003/11/12
		_	US-PGPUB;	11:57
	I		EPO; JPO;	
	1		DERWENT	
-	2	20010011764.pn.	USPAT;	2003/11/12
	1		US-PGPUB;	11:58
	İ		EPO; JPO;	
	I		DERWENT	
_	2	20010011764.pn.	USPAT;	2003/11/12
	"		US-PGPUB;	11:58
	1		EPO; JPO;	
	1		DERWENT	Į į
1_	1	20010011764.pn. and wire	USPAT;	2003/11/12
-	1	20010011/04.pm. and wire	US-PGPUB;	12:19
	1			** • * *
	1		EPO; JPO;	1
1	1	00010011764	DERWENT	2002/11/12
-	1	20010011764.pn. and (reflow same solder)	USPAT;	2003/11/12
1			US-PGPUB;	13:44
1			EPO; JPO;	1
			DERWENT	
-	1		USPAT;	2003/11/12
		same diffusion)	US-PGPUB;	13:47
			EPO; JPO;	
			DERWENT	1

	·			
-	1	20010011764.pn. and (reflow same solder	USPAT;	2003/11/12
		same (diffusion or diffus\$3))	US-PGPUB;	13:48
			EPO; JPO;]
			DERWENT	1
-	2	6133065.pn.	USPAT;	2003/11/17
		-	US-PGPUB;	07:48
			EPO; JPO;	
			DERWENT	
_	2	6335104.pn.	USPAT;	2003/11/17
		-	US-PGPUB;	07:50
			EPO; JPO;	
			DERWENT	
-	2	20010020745.pn.	USPAT;	2003/11/17
		-	US-PGPUB;	07:59
			EPO; JPO;	
			DERWENT	
_	2	6335104.pn.	USPAT;	2003/11/17
		-	US-PGPUB;	08:00
			EPO; JPO;	
[DERWENT	
_	2	20030143830.pn.	USPAT;	2003/11/17
	_	<u> </u>	US-PGPUB;	08:01
			EPO; JPO;	
	'		DERWENT	
_	2	20030107137.pn.	USPAT;	2003/11/17
	_	•	US-PGPUB;	08:02
	1		EPO; JPO;	
			DERWENT	
-	2	20010011764.pn.	USPAT;	2003/11/17
	_	•	US-PGPUB;	08:04
			EPO; JPO;	
			DERWENT	
_	2	20010020745.pn.	USPAT;	2003/11/17
		•	US-PGPUB;	08:04
			EPO; JPO;	
			DERWENT	
_	2	6133065.pn.	USPAT;	2003/12/02
ł		•	US-PGPUB;	18:10
			EPO; JPO;	
			DERWENT	
_	2	20030143830.pn.	USPAT;	2003/12/02
	_	•	US-PGPUB;	18:26
			EPO; JPO;	
I	I	l .	1	1